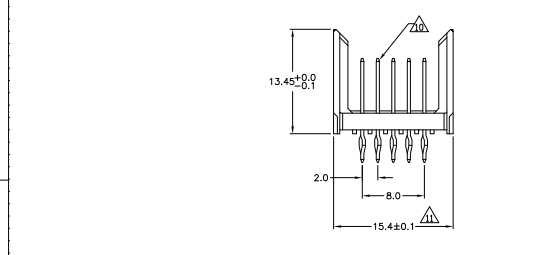
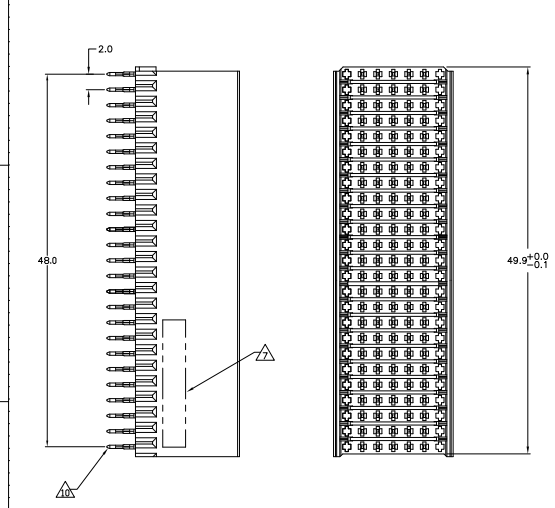
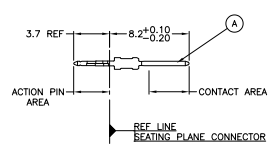


CONNECTOR ASSEMBLY  
EXEMPLARY LOADED



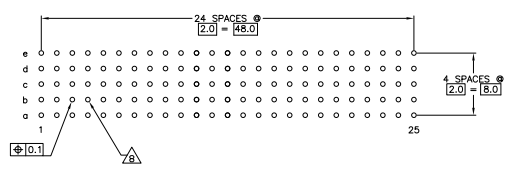
CONTACT DIMENSIONS  
SCALE 5:1



CONTACT LAYOUT

	z	a	b	c	d	e	f
1	A	A	A	A	A		
2	A	A	A	A	A		
3	A	A	A	A	A		
4	A	A	A	A	A		
5	A	A	A	A	A		
6	A	A	A	A	A		
7	A	A	A	A	A		
8	A	A	A	A	A		
9	A	A	A	A	A		
10	A	A	A	A	A		
11	A	A	A	A	A		
12	A	A	A	A	A		
13	A	A	A	A	A		
14	A	A	A	A	A		
15	A	A	A	A	A		
16	A	A	A	A	A		
17	A	A	A	A	A		
18	A	A	A	A	A		
19	A	A	A	A	A		
20	A	A	A	A	A		
21	A	A	A	A	A		
22	A	A	A	A	A		
23	A	A	A	A	A		
24	A	A	A	A	A		
25	A	A	A	A	A		

RECOMMENDED PCB-HOLE LAYOUT  
COMPONENT SIDE SHOWN



PLATED THRU HOLES PARAMETERS  
REFERENCE APPLICATION SPECIFICATION

3-100141-0	3-100141-0
1-100141-9	1-100141-9
100141-9	100141-9
100141-4	100141-4
100141-1	100141-1
FINISH	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT. **TE** HELIX **TE** HELIX

DATE	108-19082	DATE	108-19082
REVISION	114-19029	REVISION	114-19029
CUSTOMER DRAWING	A100779	CUSTOMER DRAWING	A100779

MALE ASSEMBLY, 2-PACK 2mm HM, TYPE B

SIZE: 4:1 SHEET: 1 OF 2

LOC	DIST	REVISIONS					
AD	00	P	LN	DESCRIPTION	DATE	BY	APPD
				SEE SHEET 1			

- ▲ MATERIAL:  
CONTACT: PHOSPHOR BRONZE.  
HOUSING: GLASS-FILLED POLYESTER.
- ▲ GENERAL PLATING SPECIFICATION: UNDERPLATING  
(ENTIRE CONTACT): 1.27μm MIN NICKEL AND ACTION  
PIN: 0.5μm MIN TIN/LEAD.  
FOR PLATING OF MATING SURFACES SEE APPLICABLE  
SPECIFICATION REFERENCE FOR EACH DASH NUMBER.
- ▲ CONFORMS TO ALL TESTING ACCORDING TO IEC 61076-4-101  
PERFORMANCE LEVEL 2.
- ▲ CONFORMS TO ALL TESTING ACCORDING TO IEC 61076-4-101  
PERFORMANCE LEVEL 1.
- ▲ CONNECTOR TESTED AND QUALIFIED AGAINST TELCORDIA GR-1217-CORE QUALITY LEVEL 3,  
CENTRAL OFFICE APPLICATIONS.
- ▲ CONNECTOR TESTED AND QUALIFIED AGAINST TELCORDIA GR-1217-CORE QUALITY LEVEL 3,  
CONTROLLED ENVIRONMENT APPLICATIONS.
- ▲ CONNECTOR MARKED WITH PART NUMBER AND DATE CODE.  
ADDITIONAL CHARACTERISTICS OR MARKINGS, AS WELL AS THE LOCATION OF THE MARKINGS,  
MAY BE ADDED FOR TRACEABILITY BASED UPON MANUFACTURERS DISCRETION.
- ▲ PLATED-THROUGH HOLES AT 2x2mm SQUARE GRID  
PATTERN DEFINED BY CONTACT LAYOUT.
- ▲ FOR ACTUAL PIN LOADING SEE "CONTACT LAYOUT".
- ▲ FOR ACTUAL PIN DIMENSIONS SEE "CONTACT DIMENSIONS".
- ▲ TO BE MEASURED AT BOTTOM OF SHROUD.
- ▲ CONNECTOR LUBRICATED WITH BELCORP APPROVED LUBRICANT,  
TECHNICAL REFERENCE: TR-NWT-001217 ISSUE 1, SEP 1992.
- ▲ 0.76μm MIN GOLD PLATING AT MATING SURFACES.

[illegible]